

MC74VHC14

Hex Schmitt Inverter

The MC74VHC14 is an advanced high speed CMOS Schmitt inverter fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

Pin configuration and function are the same as the MC74VHC04 but the inputs have hysteresis and, with its Schmitt trigger function, the VHC14 can be used as a line receiver which will receive slow input signals.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output. The inputs tolerate voltages up to 7.0 V, allowing the interface of 5.0 V systems to 3.0 V systems.

Features

- High Speed: $t_{PD} = 5.5 \text{ ns}$ (Typ) at $V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 2.0 \mu\text{A}$ (Max) at $T_A = 25^\circ\text{C}$
- High Noise Immunity: $V_{NIH} = V_{NIL} = 28\% V_{CC}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 2.0 V to 5.5 V Operating Range
- Low Noise: $V_{OLP} = 0.8 \text{ V}$ (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: Human Body Model $> 2000 \text{ V}$;
Machine Model $> 200 \text{ V}$
- Chip Complexity: 60 FETs or 15 Equivalent Gates
- Pb-Free Packages are Available

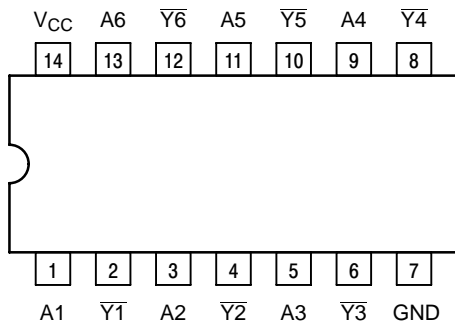


Figure 1. 14-Lead Pinout (Top View)



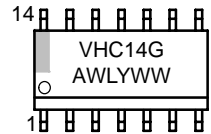
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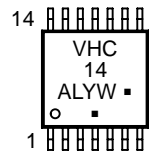
MARKING DIAGRAMS



SOIC-14
D SUFFIX
CASE 751A



TSSOP
DT SUFFIX
CASE 948G



A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package
(Note: Microdot may be in either location)

FUNCTION TABLE

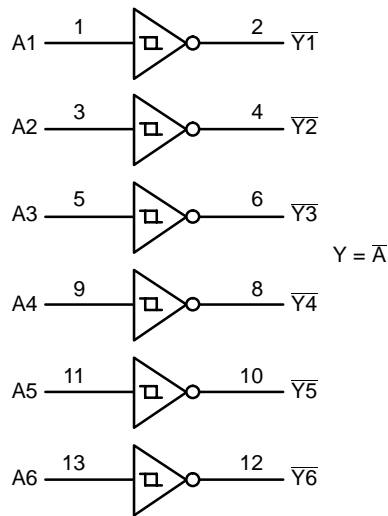
Inputs	Outputs
A	Y
L	H
H	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Figure 2. Logic Diagram

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V_{CC}	Positive DC Supply Voltage	-0.5 to +7.0	V	
V_{IN}	Digital Input Voltage	-0.5 to +7.0	V	
V_{OUT}	DC Output Voltage	-0.5 to $V_{CC} + 0.5$	V	
I_{IK}	Input Diode Current	-20	mA	
I_{OK}	Output Diode Current	± 20	mA	
I_{OUT}	DC Output Current, per Pin	± 25	mA	
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 75	mA	
P_D	Power Dissipation in Still Air	SOIC TSSOP	200 180	mW
T_{STG}	Storage Temperature Range	-65 to +150	$^{\circ}\text{C}$	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	>2000 >200 N/A	V
$I_{LATCHUP}$	Latchup Performance	Above V_{CC} and Below GND at 125 $^{\circ}\text{C}$ (Note 4)	± 300	mA
θ_{JA}	Thermal Resistance, Junction-to-Ambient	SOIC TSSOP	143 164	$^{\circ}\text{C}/\text{W}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Tested to EIA/JESD22-A114-A.
2. Tested to EIA/JESD22-A115-A.
3. Tested to JESD22-C101-A.
4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V_{CC}	DC Supply Voltage	2.0	5.5	V
V_{IN}	DC Input Voltage	0	5.5	V
V_{OUT}	DC Output Voltage	0	V_{CC}	V
T_A	Operating Temperature Range, All Package Types	-55	125	$^{\circ}\text{C}$
t_r, t_f	Input Rise or Fall Time	-	No limit No limit	ns/V
	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	-	-	-

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DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CC} V	T _A = 25°C			-55°C ≤ T _A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	
V _{T+}	Positive Threshold Voltage (Figure 5)		3.0			2.20		2.20	V
			4.5			3.15		3.15	
			5.5			3.85		3.85	
V _{T-}	Negative Threshold Voltage (Figure 5)		3.0	0.9			0.90		V
			4.5	1.35			1.35		
			6.0	1.65			1.65		
V _H	Hysteresis Voltage (Figure 5)		3.0	0.30		1.20	0.30	1.20	V
			4.5	0.40		1.40	0.40	1.40	
			5.5	0.50		1.60	0.50	1.60	
V _{OH}	Minimum High-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{OH} = -50 μA	2.0	1.9	2.0		1.9		V
			3.0	2.9	3.0		2.9		
		4.5	4.4	4.5		4.4			
		V _{in} = V _{IH} or V _{IL} I _{OH} = -4 mA I _{OH} = -8 mA	3.0	2.58			2.48		
4.5	3.94				3.80				
V _{OL}	Maximum Low-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{OL} = 50 μA	2.0		0.0	0.1		0.1	V
			3.0		0.0	0.1		0.1	
			4.5		0.0	0.1		0.1	
		V _{in} = V _{IH} or V _{IL} I _{OL} = 4 mA I _{OL} = 8 mA	3.0		0.36		0.44		
4.5			0.36		0.44				
I _{in}	Maximum Input Leakage Current	V _{in} = 5.5 V or GND	0 to 5.5			± 0.1		± 1.0	μA
I _{CC}	Maximum Quiescent Supply Current	V _{in} = V _{CC} or GND	5.5			2.0		20.0	μA

AC ELECTRICAL CHARACTERISTICS (Input t_r = t_f = 3.0 ns)

Symbol	Parameter	Test Conditions	T _A = 25°C			-55°C ≤ T _A ≤ 125°C		Unit
			Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, A or B to \bar{Y}	V _{CC} = 3.3 ± 0.3 V C _L = 15 pF C _L = 50 pF		8.3 10.8	12.8 16.3	1.0 1.0	15.0 18.5	ns
		V _{CC} = 5.0 ± 0.5 V C _L = 15 pF C _L = 50 pF		5.5 7.0	8.6 10.6	1.0 1.0	10.0 12.0	
C _{in}	Maximum Input Capacitance			4 10			10	pF

C _{PD}	Power Dissipation Capacitance (Note 5)	Typical @ 25°C, V _{CC} = 5.0 V		pF
		21		

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}/6 (per buffer). C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

NOISE CHARACTERISTICS (Input t_r = t_f = 3.0 ns, C_L = 50 pF, V_{CC} = 5.0 V)

Symbol	Characteristic	T _A = 25°C		Unit
		Typ	Max	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	0.4	0.8	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	-0.4	-0.8	V
V _{IHD}	Minimum High Level Dynamic Input Voltage		3.5	V
V _{ILD}	Maximum Low Level Dynamic Input Voltage		1.5	V

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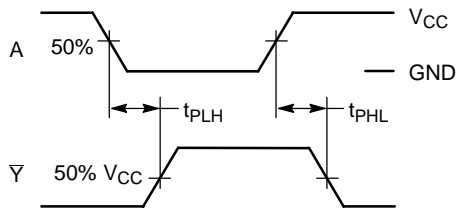
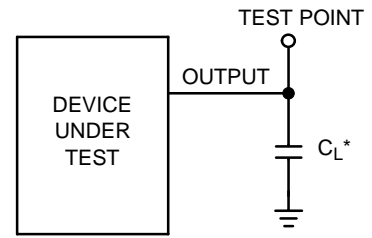


Figure 3. Switching Waveforms



*Includes all probe and jig capacitance

Figure 4. Test Circuit

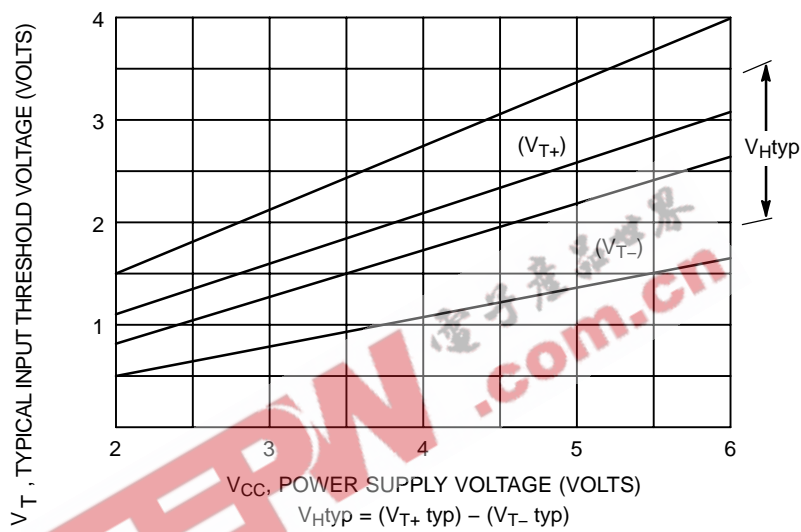


Figure 5. Typical Input Threshold, V_{T+} , V_{T-} versus Power Supply Voltage

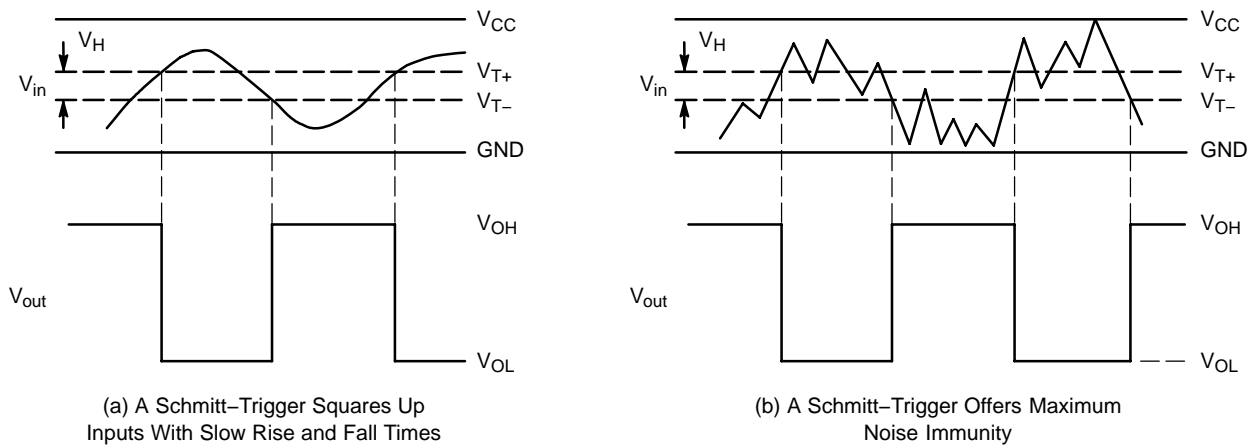


Figure 6. Typical Schmitt-Trigger Applications

MC74VHC14

ORDERING INFORMATION

Device	Package	Shipping†
MC74VHC14D	SOIC-14	55 Units / Rail
MC74VHC14DG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74VHC14DR2	SOIC-14	2500 / Tape & Reel
MC74VHC14DR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC74VHC14DT	TSSOP-14*	96 Units / Rail
MC74VHC14DTG	TSSOP-14*	96 Units / Rail
MC74VHC14DTR2	TSSOP-14*	2500 / Tape & Reel
MC74VHC14DTR2G	TSSOP-14*	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

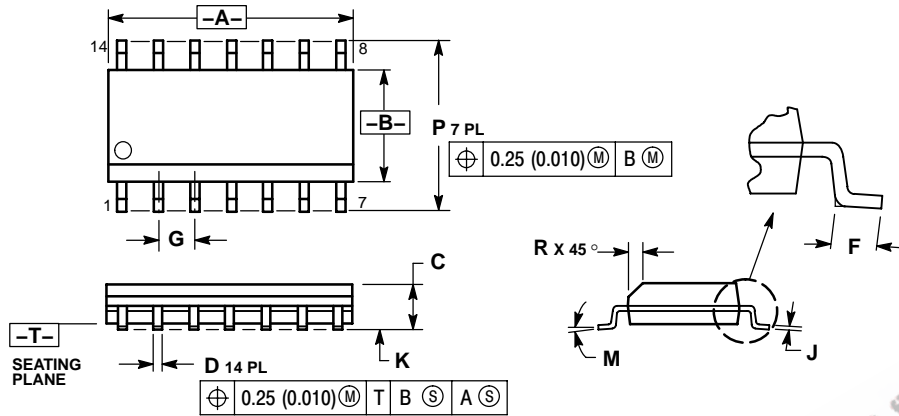
*This package is inherently Pb-Free.

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MC74VHC14

PACKAGE DIMENSIONS

SOIC-14
D SUFFIX
CASE 751A-03
ISSUE G



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

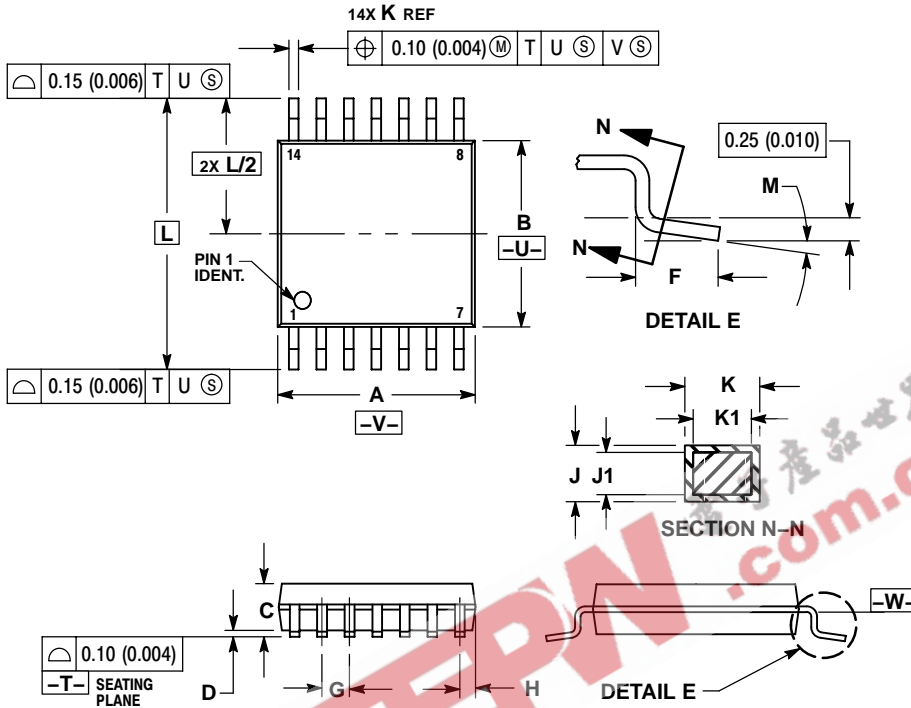
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

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MC74VHC14

PACKAGE DIMENSIONS

TSSOP-14
DT SUFFIX
CASE 948G-01
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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